

**Dual N-Ch Fast Switching MOSFETs**
**Description**

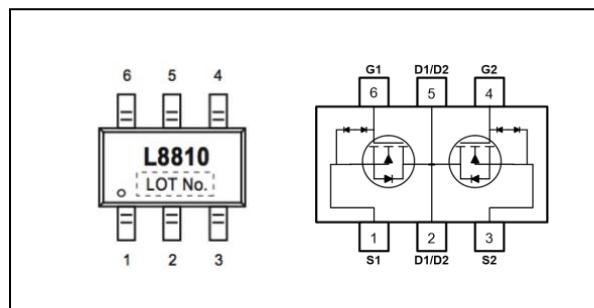
The HSW8810 is the low RDSON trenched N-CH MOSFETs with robust ESD protection. This product is suitable for Lithium-ion battery pack applications.

The HSW8810 meet the RoHS and Green Product requirement with full function reliability approved.

**Product Summary**

V <sub>DS</sub>	20	V
R <sub>DS(ON),max</sub>	20	mΩ
I <sub>D</sub>	6	A

- Green Device Available
- Super Low Gate Charge
- ESD Protection
- Excellent CdV/dt effect decline
- Advanced high cell density Trench

**SOT23-6L Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current <sub>1</sub>	6	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current <sub>1</sub>	4.8	A
I <sub>DM</sub>	Pulsed Drain Current <sub>2</sub>	24	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sub>3</sub>	1.25	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sub>1</sub>	---	100	°C/W

**N-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =3A	15	16.5	20	mΩ
		V <sub>GS</sub> =4.0V , I <sub>D</sub> =3A	15.5	17	20.5	
		V <sub>GS</sub> =3.7V , I <sub>D</sub> =3A	16	17.5	21	
		V <sub>GS</sub> =3.1V , I <sub>D</sub> =3A	17	18.5	23	
		V <sub>GS</sub> =2.5V , I <sub>D</sub> =3A	18.5	21	26	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.5	0.7	1.2	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
I <sub>GS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±8V , V <sub>DS</sub> =0V	---	---	±10	uA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =3A	---	17	---	S
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =6A	---	10.4	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.3	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	2.6	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =10V , V <sub>GS</sub> =4.5V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =3A	---	3.2	---	ns
T <sub>r</sub>	Rise Time		---	9.8	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	31	---	
T <sub>f</sub>	Fall Time		---	3.6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz	---	630	---	pF
C <sub>oss</sub>	Output Capacitance		---	66	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	63	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	5.5	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	---	0.78	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t ≤10s.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I<sub>b</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



N-Channel Typical

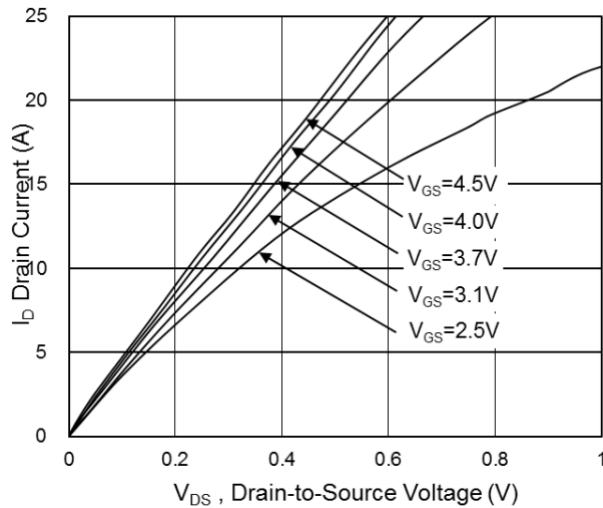


Fig.1 Typical Output Characteristics

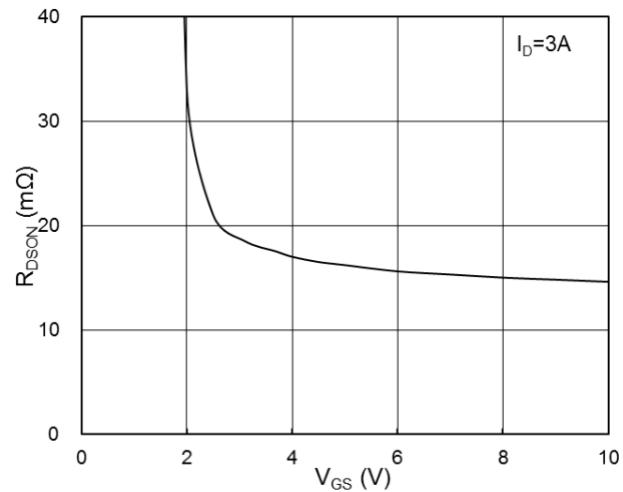


Fig.2 On-Resistance vs. Gate-Source voltage

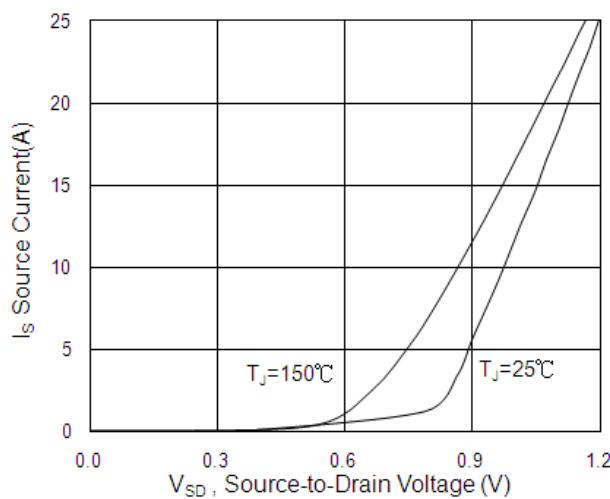


Fig.3 Forward Characteristics of Reverse

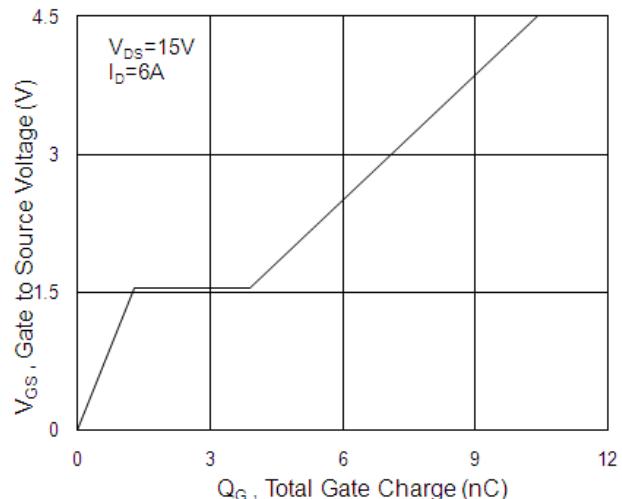


Fig.4 Gate-Charge Characteristics

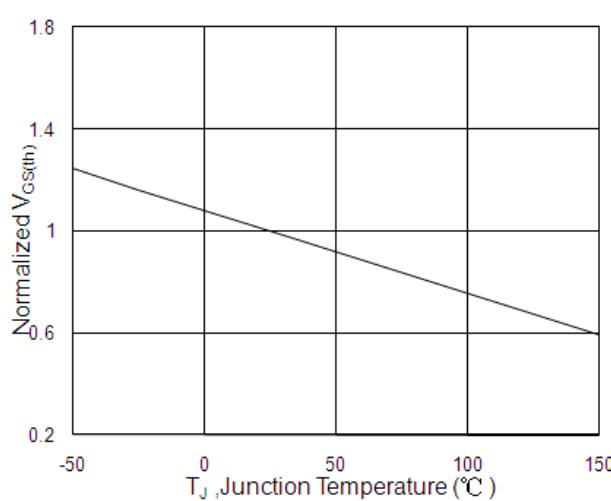


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

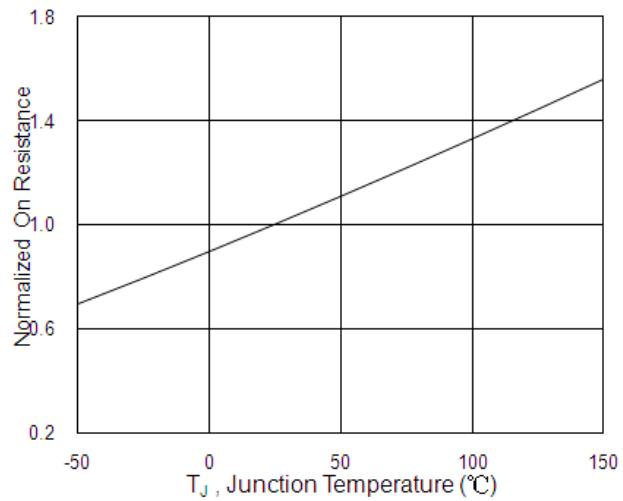


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



Dual N-Ch Fast Switching MOSFETs

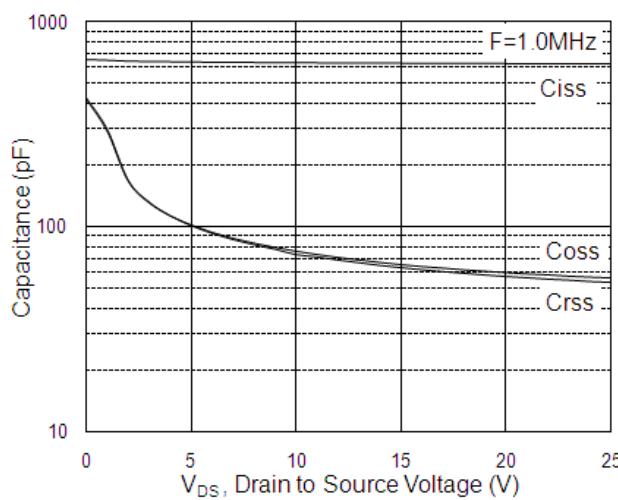


Fig.7 Capacitance

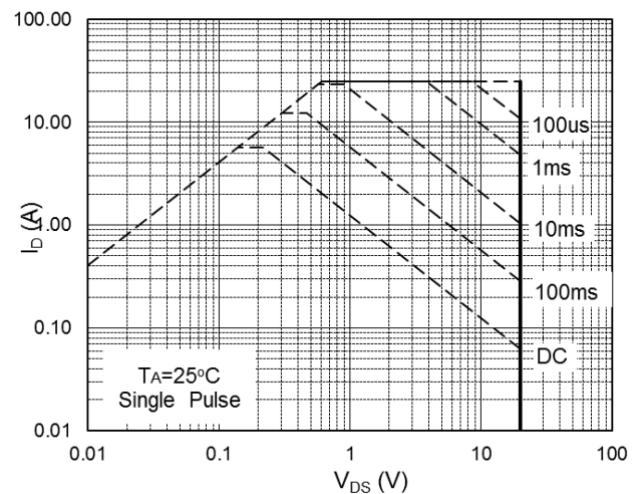


Fig.8 Safe Operating Area

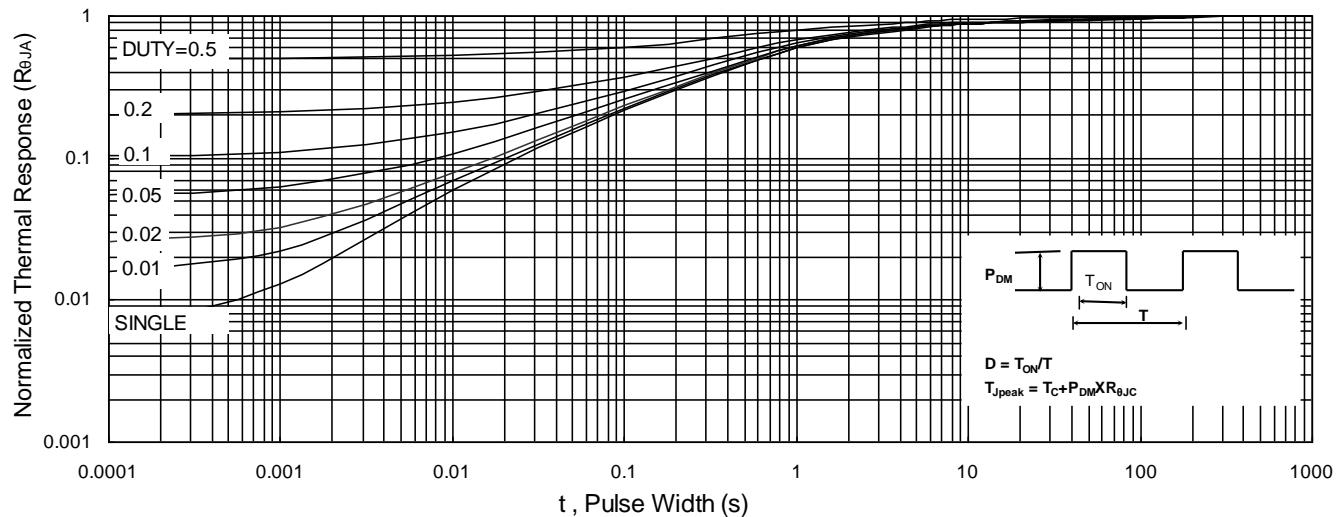


Fig.9 Normalized Maximum Transient Thermal Impedance

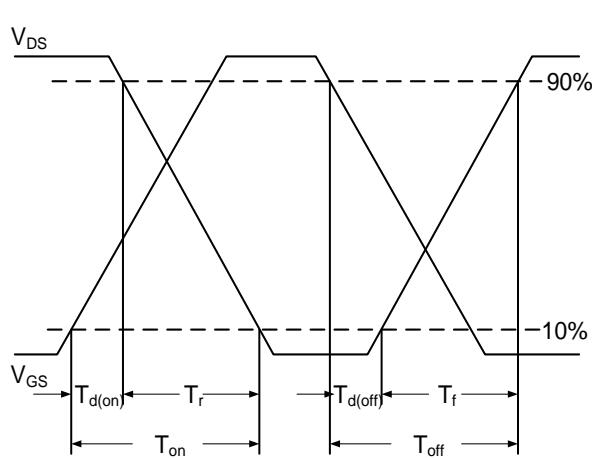


Fig.10 Switching Time Waveform

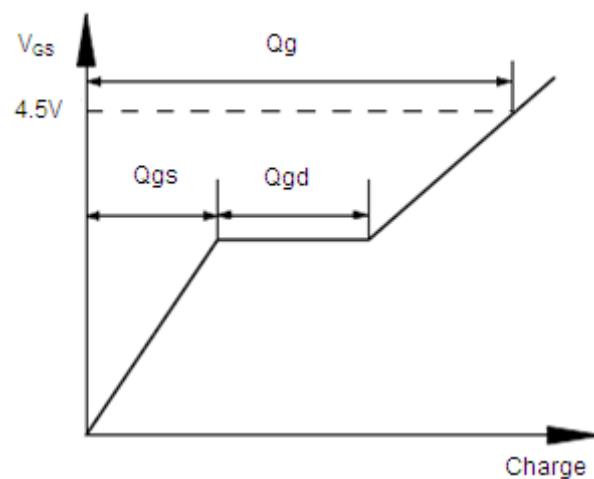
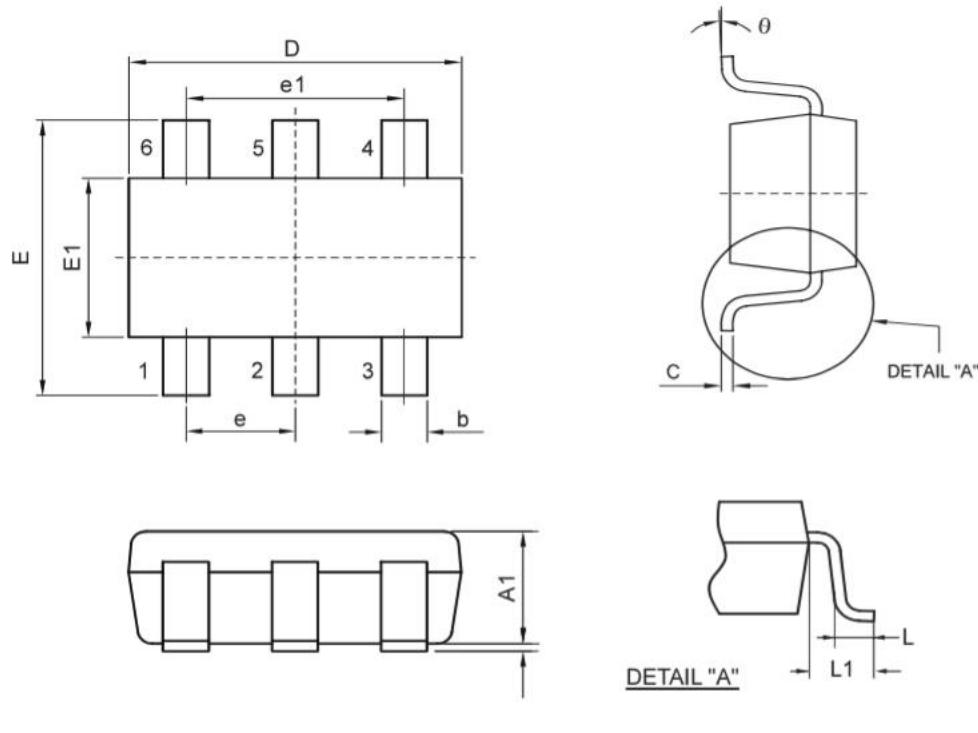


Fig.11 Gate Charge Waveform



## SOT23-6L Package Outline Dimensions



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D	2.692	3.099	0.106	0.122
E	2.591	3.000	0.102	0.118
E1	1.397	1.803	0.055	0.071
e	0.950 REF.		0.037 REF.	
e1	1.900 REF.		0.075 REF.	
b	0.300	0.500	0.012	0.020
C	0.080	0.200	0.003	0.008
A	0.000	0.100	0.000	0.004
A1	0.700	1.200	0.028	0.048
L	0.300	0.600	0.012	0.024
L1	0.600 REF.		0.023 REF.	
θ	0°	9°	0°	9°

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